

Title (en)
PHOTOCATALYTIC SPUTTERING TARGETS AND METHODS FOR THE PRODUCTION AND USE THEREOF

Title (de)
TARGETS FÜR DAS PHOTOKATALYTISCHE SPUTTERN UND VERFAHREN ZUR HERSTELLUNG UND VERWENDUNG DAVON

Title (fr)
CIBLES DE PULVERISATION PHOTOCATALYTIQUES ET PROCEDES DE PRODUCTION ET D'UTILISATION DE CES CIBLES

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EP 1352105 A2 20031015 (EN)

Application
EP 02719697 A 20020114

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• EP 0200378 W 20020114
• US 26287801 P 20010117

Abstract (en)
[origin: WO02057508A2] The invention provides sputtering targets that are adapted for the deposition of photocatalytic coatings. The invention also provides methods for producing sputtering targets of this nature. The methods comprise forming sputtering targets from photocatalyst particles that are free of inert particle treatment. The photocatalyst particles are plasma sprayed onto the target base. For example, a preferred embodiment of the invention comprises plasma spraying uncoated titanium dioxide particles onto a target base. The titanium dioxide particles are optionally plasma sprayed under conditions that result in the target base being coated with substoichiometric titanium oxide, TiO_x, where x is less than 2. The invention also provides substrates coated by the disclosed sputtering methods.
[origin: WO02057508A2] The invention comprises forming sputtering targets from photocatalyst particles that are free of inert particle treatment. The photocatalyst particles are plasma sprayed onto the target base. For example, a preferred embodiment of the invention comprises plasma spraying uncoated titanium dioxide particles onto a target base. The titanium dioxide particles are optionally plasma sprayed under conditions that result in the target base being coated with substoichiometric titanium oxide, TiO_x, where x is less than 2.

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